MA2Z720

Silicon epitaxial planar type

For high frequency rectification

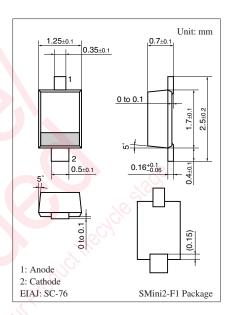
■ Features

- Forward current (Average) I_{F(AV)} = 500 mA rectification is possible
- High-density mounting is possible

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V _{RM}	40	V
Forward current (Average)	$I_{F(AV)}$	500	mA
Non-repetitive peak forward surge current *	I_{FSM}	2	A
Junction temperature	T_{j}	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

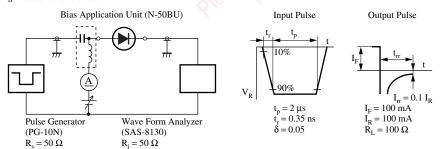


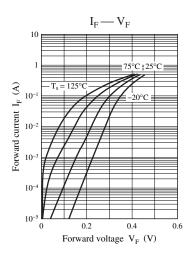
Marking Symbol: 2L

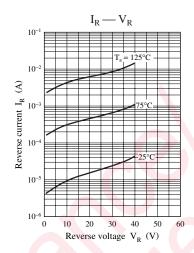
■ Electrical Characteristics $T_a = 25$ °C ± 3°C

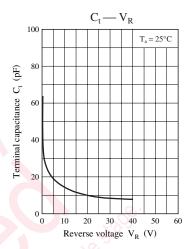
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 500 \text{ mA}$	100	0,	0.55	V
Reverse current	I_R	$V_R = 35 \text{ V}$)	100	μΑ
Terminal capacitance	C_t	$V_R = 0 V, f = 1 MHz$	1.90	60		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		5		ns
		$I_{rr} = 0.1 I_{R}, R_{L} = 100 \Omega$				

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 400 MHz.
 - 4.*: t_{rr} measurement circuit









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